## INTEGRATED CIRCUITS

## DATA SHEET

# **74LVC04A**Hex inverter

Product specification Supersedes data of 1997 Mar 28 IC24 Data Handbook 1997 Jun 30





Hex inverter 74LVC04A

#### **FEATURES**

- Wide supply range of 1.2V to 3.6V
- Complies with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 5-volt tolerant inputs, for interfacing with 5-volt logic

#### **DESCRIPTION**

The 74LVC04A is a high-performance, low-power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V/5 V environment.

The 74LVC04A provides six inverting buffers.

#### **QUICK REFERENCE DATA**

GND = 0 V;  $T_{amb} = 25^{\circ}C$ ;  $t_r = t_f \le 2.5 \text{ ns}$ 

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay nA to nY	$C_L = 50 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	2.5	ns
C <sub>I</sub>	Input capacitance		5.0	pF
C <sub>PD</sub>	Power dissipation capacitance per gate	Notes 1 and 2	25	pF

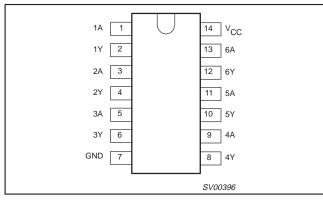
#### NOTES:

- 1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W)  $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:  $f_i$  = input frequency in MHz;  $C_L$  = output load capacity in pF;  $f_o$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;  $\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.
- 2. The condition is  $V_I = GND$  to  $V_{CC}$ .

#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic SO	-40°C to +85°C	74LVC04A D	74LVC04A D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC04A DB	74LVC04A DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC04A PW	74LVC04APW DH	SOT402-1

#### **PIN CONFIGURATION**

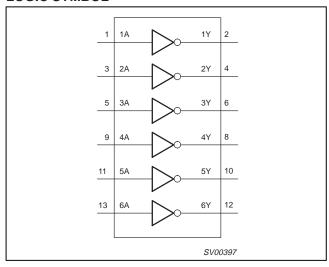


#### **PIN DESCRIPTION**

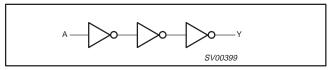
PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 3, 5, 9, 11, 13 1A to 6		Data inputs
2, 4, 6, 8, 10, 12	1Y to 6Y	Data outputs
7	GND	Ground (0 V)
14 V <sub>CC</sub>		Positive supply voltage

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## **LOGIC SYMBOL**



## **LOGIC DIAGRAM (ONE GATE)**



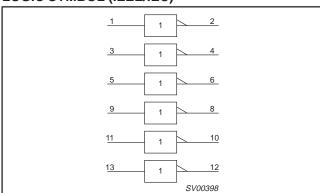
## **FUNCTION TABLE**

INPUTS	OUTPUTS
nA	nY
L	Н
Н	L

#### NOTES:

H = HIGH voltage level L = LOW voltage level

## LOGIC SYMBOL (IEEE/IEC)



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#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	CONDITIONS	LIM	ITS	UNIT
STWIBOL	PARAIVIETER	CONDITIONS	MIN	MAX	UNIT
V <sub>CC</sub>	DC supply voltage (for max. speed performance)		2.7	3.6	V
V <sub>CC</sub>	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC Input voltage range		0	5.5	V
Vo	DC output voltage range		0	V <sub>CC</sub>	V
T <sub>amb</sub>	Operating ambient temperature range in free-air		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7 \text{V}$ $V_{CC} = 2.7 \text{ to } 3.6 \text{V}$	0	20 10	ns/V

#### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +6.5	V
I <sub>IK</sub>	DC input diode current	V <sub>I</sub> < 0	-50	mA
V <sub>I</sub>	DC input voltage	Note 2	-0.5 to +5.5	V
I <sub>OK</sub>	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
V <sub>O</sub>	DC output voltage	Note 2	V <sub>CC</sub> + 0.5	V
I <sub>O</sub>	DC output source or sink current	$V_O = 0$ to $V_{CC}$	±50	mA
I <sub>GND</sub> , I <sub>CC</sub>	DC V <sub>CC</sub> or GND current		± 100	mA
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
P <sub>TOT</sub>	Power dissipation per package  – plastic mini-pack (SO)  – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

#### NOTES:

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<sup>1.</sup> Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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#### DC CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			L	IMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	40°C to	+85°C	UNIT	
			MIN	TYP <sup>1</sup>	MAX		
V	HICH lovel Input voltage	V <sub>CC</sub> = 1.2V	V <sub>CC</sub>			V	
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V	2.0			]	
	LOW love land valtage	V <sub>CC</sub> = 1.2V			GND		
V <sub>IL</sub>	LOW level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V			0.8	]	
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -12$ mA	V <sub>CC</sub> -0.5				
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	HIGH level output voltage	$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -100\mu A$	V <sub>CC</sub> -0.2 V <sub>CC</sub>				
V <sub>OH</sub>		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -18$ mA	V <sub>CC</sub> -0.6			\ \	
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -24$ mA	V <sub>CC</sub> -0.8				
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 12$ mA			0.40		
V <sub>OL</sub>	LOW level output voltage	$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 100\mu A$			0.20	V	
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 24$ mA			0.55	1	
1 <sub>1</sub>	Input leakage current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = 5.5V or GND		±0.1	±5	μΑ	
I <sub>CC</sub>	Quiescent supply current	$V_{CC} = 3.6V$ ; $V_I = V_{CC}$ or GND; $I_O = 0$		0.1	10	μΑ	
Δl <sub>CC</sub>	Additional quiescent supply current per input pin	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.6V; I_O = 0$		5	500	μА	

#### NOTES:

## **AC CHARACTERISTICS**

GND = 0 V;  $t_r = t_f \le 2.5 \text{ ns}$ ;  $C_L = 50 \text{ pF}$ 

			LIMITS							
SYMBOL	PARAMETER	AMETER WAVEFORM		$= 3.3V \pm 0$	).3V	'	/ <sub>CC</sub> = 2.7\	/	V <sub>CC</sub> = 1.2V	UNIT
			MIN	TYP <sup>1</sup>	MAX	MIN	TYP	MAX	TYP	
t <sub>PHL</sub> / t <sub>PLH</sub>	Propagation delay nA to nY	1	1.5	2.5	4.5	1.5	3.2	5.5	16.0	ns

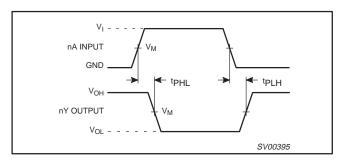
#### NOTE:

## **AC WAVEFORMS**

 $V_{M}$  = 1.5 V at  $V_{CC}\,\geq\,2.7$  V

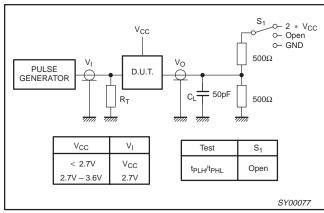
 $V_M = 0.5 \bullet V_{CC}$  at  $V_{CC} < 2.7 V$ 

 $\mbox{V}_{\mbox{OL}}$  and  $\mbox{V}_{\mbox{OH}}$  are the typical output voltage drop that occur with the output load.



Waveform 1. Input (nA) to output (nY) propagation delays.

## **TEST CIRCUIT**



Waveform 2. Load circuitry for switching times.

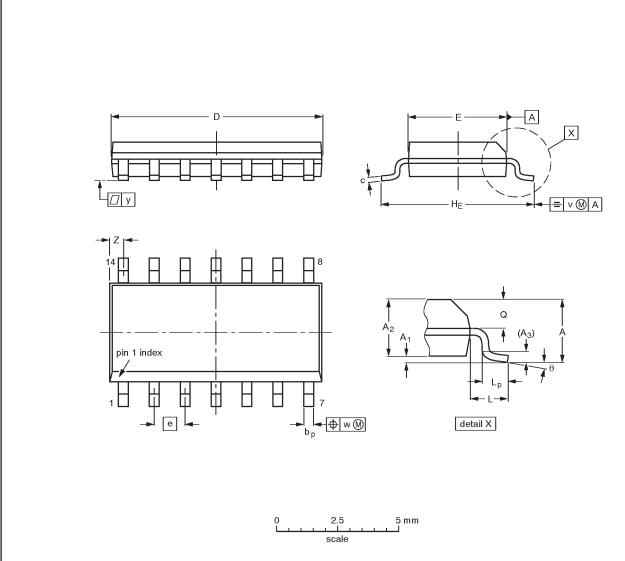
<sup>1.</sup> All typical values are at  $V_{CC}$  = 3.3V and  $T_{amb}$  = 25°C.

<sup>1.</sup> These typical values are at  $V_{CC}$  = 3.3V and  $T_{amb}$  = 25°C.

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## SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	<b>A</b> <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Ø	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01		0.0098 0.0075		0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

#### Note

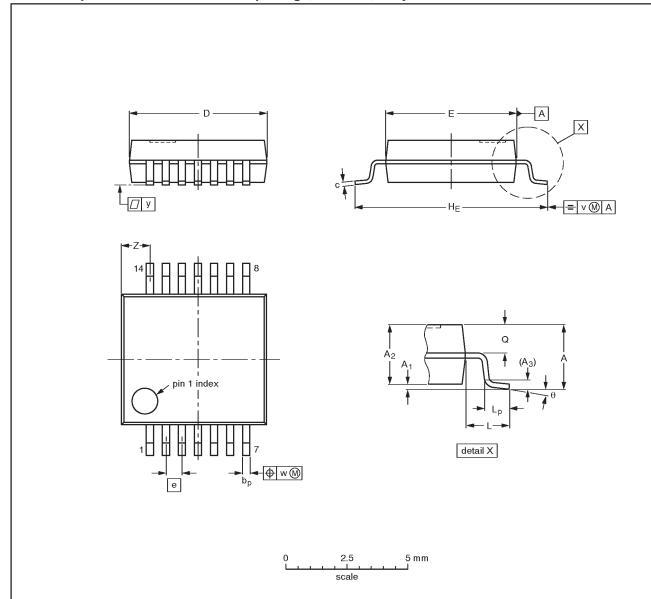
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE	OUTLINE		REFER	EUROPEAN	ISSUE DATE		
	VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
	SOT108-1	076E06S	MS-012AB			<del>91-08-13-</del> 95-01-23	

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## SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	<b>A</b> <sub>3</sub>	bp	c	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

#### Note

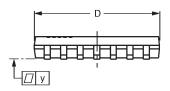
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

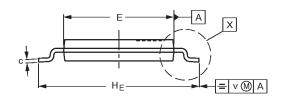
OUTLINE		REFER	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT337-1		MO-150AB			<del>-95-02-04</del> 96-01-18

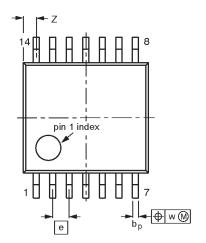
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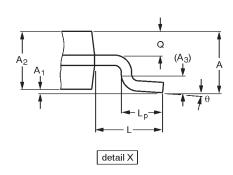
TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

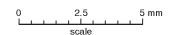
SOT402-1











#### DIMENSIONS (mm are the original dimensions)

UN	IT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	рb	c	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Ø	v	w	у	Z <sup>(1)</sup>	θ
mı	n	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE	
SOT402-1		MO-153				<del>-94-07-12</del> 95-04-04	

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## **NOTES**

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DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.				
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.				
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.				

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